

In the claims:

Please amend the claims as follows:

1. (Currently amended): Electronic component, ~~particularly a surface mountable radiation emitting and/or radiation-sensitive electro-optical component (1), with having~~ a plastic housing (10) that includes at least one metallic soldering area (4), characterized in that the surface of the plastic housing (10), except for the metallic soldering area (4), is at least partially covered by an anti-solder coating (6).
2. (Currently amended): Electronic component as in Claim 1, characterized in that the anti-solder coating (6) essentially consists of siloxane.
3. (Currently amended): Electronic component as in Claim 1, characterized in that the anti-solder coating (6) essentially consists of polysiloxane.
4. (Currently amended): Electronic component as in claim 1, characterized in that the anti-solder coating (6) is essentially based on methyl-polysiloxane.
5. (Currently amended): Electronic component as in claim 1, characterized in that the anti-solder coating (6) is essentially based on dimethyl-polysiloxane.
6. (Currently amended): Electronic component as in claim 1, characterized in that the anti-solder coating (6) is essentially based on polyether-modified dimethyl-polysiloxane.
7. (Currently amended): Electronic component as in claim 1, characterized in that the plastic housing (14) contains a radiation-emitting and/or radiation-detecting semiconductor element that is embedded in transparent plastic for the emitted and/or received radiation.

Claims 8-26 (Withdrawn)

27. (New) Electronic component as in claim 1 wherein said component is a surface-mountable radiation-emitting and/or radiation-sensitive electro-optical component.

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28. (New) Electronic component as in claim 1 wherein said component is an unsoldered component.